YASKAWA

Basic Specifications:

Model: XU-ACP330-R00 (SEMISTAR-PER1130)

Item		Specifications
Wafer size		300 mm
Fiducial Recognition		Notch
Wafer Material		Silicon or Quartz *1
Light source of sensor		RED LED
Alignment accuracy *2	Rotation	±0.1°
	Wafer center	±0.1mm
Alignment time *3		Less than 5.0 sec
Motion Range		Mechanical motion range : No hard stop (unlimited) (With soft ware motion stop)
		Lifter part stroke: 17mm
		Grip part stroke: 4mm
Capture range		304mm
Clean Class		ISO Class1 *4
Wafer holding method		Active edge grip method
Wafer detection		CCD Line sensor
Motor		AC servo motor with 20 bit Incremental Encoder (AC200V)
Detection of rotation position		Absolute encoder of a motor. There is battery for encoder backup in the body.
CDA requirement		0.21 to 0.22 MPa (30.45 to 31.9 psi) 1.5L/min
Vacuum requirement		-80 to –70 kPa, 5L/min
Approx. mass		8.8 kg

*1 The threshold value setting for the sensor is required to be reset for quartz wafers of specified user.

*2 It is a value in SEMI standard wafer. A wafer material is silicon and edge presupposes that it is smooth.

*3 Alignment time does not include

- Un-grip and lift up time when Pre-aligner grips wafer notch.
- Operation for avoiding the interference in the case of overlapping the operation domain of grips and lift

*4 It is based on measurement in Yaskawa's clean booth. Evaluation is performed above wafer in the environment of down flow 0.3 m/ sec.

Exterior

Wafer Grip: PEEK
Lift pad: PEEK
Pre Aligner Body: Anodized Aluminum and Stainless Steel.